

LM160QML High Speed Differential Comparator

Check for Samples: [LM160QML](#)

FEATURES

- Ensured High Speed: 20nS max
- Tight Delay Matching on Both Outputs
- Complementary TTL Outputs
- High Input Impedance
- Low Speed Variation with Overdrive Variation
- Fan-Out of 4
- Low Input Offset Voltage
- Series 74 TTL Compatible

DESCRIPTION

The LM160 is a very high speed differential input, complementary TTL output voltage comparator with improved characteristics over the μ A760/ μ A760C, for which it is a pin-for-pin replacement. The device has been optimized for greater speed, input impedance and fan-out, and lower input offset voltage. Typically delay varies only 3nS for overdrive variations of 5mV to 400mV.

Complementary outputs having minimum skew are provided. Applications involve high speed analog to digital convertors and zero-crossing detectors in disk file systems.

Connection Diagrams

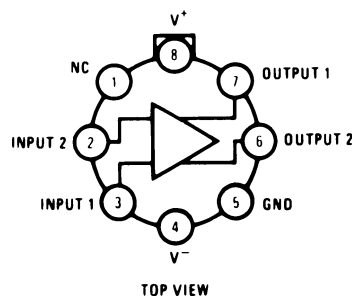


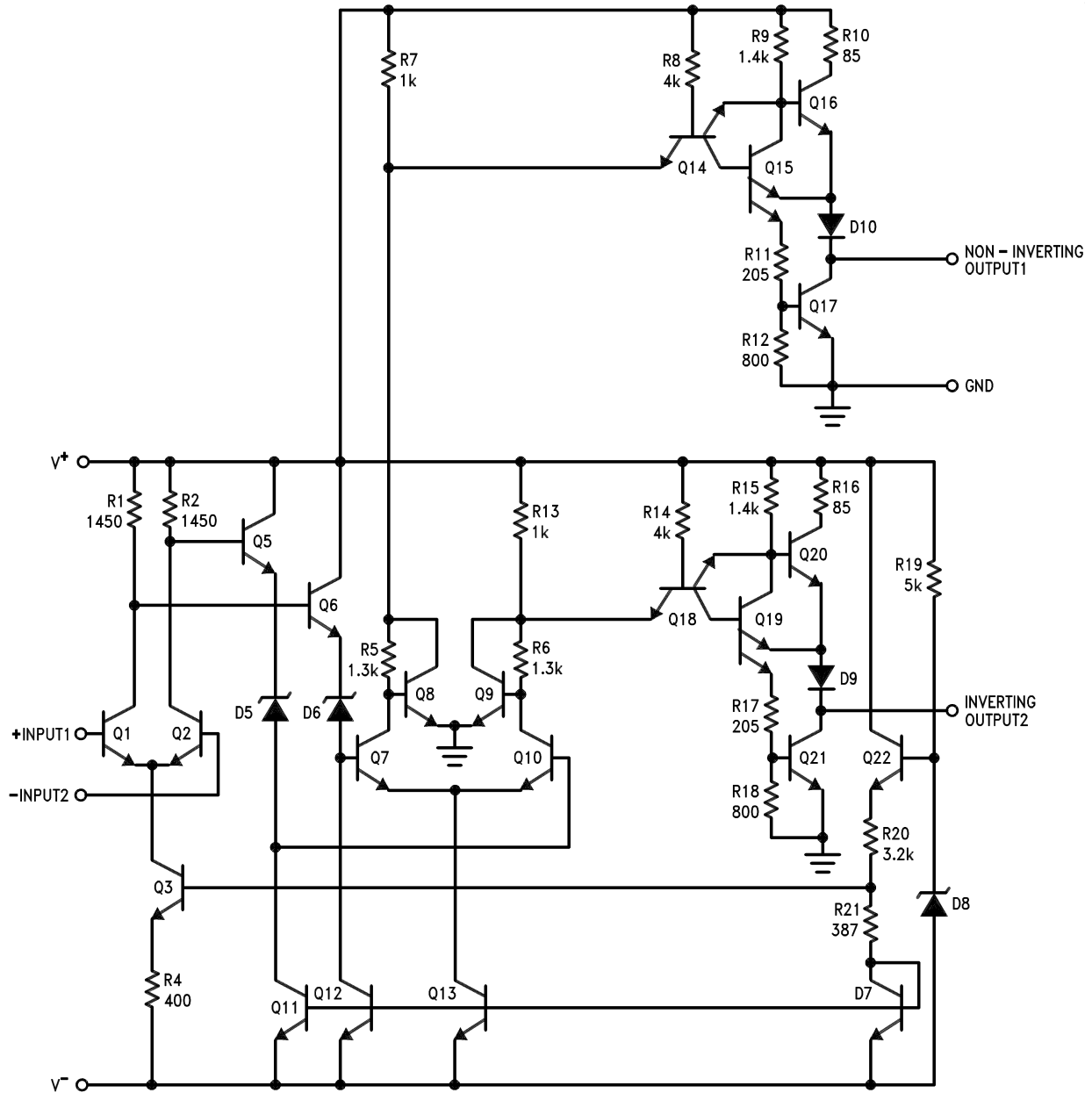
Figure 1. Metal Can Package
See Package Number LMC0008C



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Schematic Diagram



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Positive Supply Voltage			+8V
Negative Supply Voltage			-8V
Peak Output Current			20 mA
Differential Input Voltage			±5V
Input Voltage			$V^+ \geq V_I \geq V^-$
Operating Temperature Range			$-55^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$
Storage Temperature Range			$-65^\circ\text{C} \leq T_A \leq +150^\circ\text{C}$
Thermal Resistance	θ_{JA}	Still Air	165°C/W
		400 LF/min	67°C/W
	θ_{JC}		25°C/W
Lead Temperature (Soldering, 10 sec.)			260°C
ESD Tolerance ⁽²⁾			1,600V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

- (2) Human body model, 1.5 k Ω in series with 100 pF.

Quality Conformance Inspection

Mil-Std-883, Method 5005 - Group A

Subgroup	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55
12	Settling time at	+25
13	Settling time at	+125
14	Settling time at	-55

LM160H/883 Electrical Characteristics DC Parameters

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
V _{OH B}	Logical "1" Output Voltage	V _{CC} ±4.5V, I _O = -320μA		2.4		V	1, 2, 3
V _{OH A}	Logical "1" Output Voltage	V _{CC} ±4.5V, I _O = -320μA		2.4		V	1, 2, 3
V _{OL A}	Logical "0" Output Voltage	V _{CC} ±4.5V, I _O = 6.4mA			0.4	V	1, 2, 3
V _{OL B}	Logical "0" Output Voltage	V _{CC} = 4.5V, I _O = 6.4mA			0.4	V	1, 2, 3
I _{IB}	Input Bias Current	V _{CC} = ±5V, V _{IN} = 5V			20	μA	1, 2, 3
I _{CC+}	Positive Supply Current	V _{CC} = ±6.5V			32	mA	1, 2, 3
I _{CC-}	Negative Supply Current	V _{CC} = ±6.5V			-16	mA	1, 2, 3
I _{OS B}	Short Circuit Current	V _{CC} = ±4.5V		-15	-52	mA	1, 2, 3
I _{OS A}	Short Circuit Current	V _{CC} = ±4.5V		-15	-52	mA	1, 2, 3
V _{IO}	Input Offset Voltage	V _{CC} = ±5V		-5.0	5.0	mV	1, 2, 3
I _{IO}	Input Offset Current	V _{CC} = ±5V		-3.0	3.0	μA	1, 2, 3
I _I (1)	Unbalanced Input Current	V _{CC} = ±5V, V _{IN} (1) = 0, V _{IN} (2) = 5V	See ⁽¹⁾		-1.0	mA	1, 2, 3
I _I (2)	Unbalanced Input Current	V _{CC} = ±5V, V _{IN} (1) = 5V, V _{IN} (2) = 0V	See ⁽¹⁾		-1.0	mA	1, 2, 3
V _{CC}	Supply Voltage		See ⁽¹⁾	±4.5	±6.5	V	1, 2, 3
BV _{CC}	Supply Breakdown Voltage		See ⁽¹⁾	±8.0		V	1, 2, 3
V _{CM}	Common Mode Input Voltage Range	V _{CC} = ±6.5V	See ⁽¹⁾	±4.0		V	1, 2, 3
V _{Diff}	Differential Input Voltage Range		See ⁽¹⁾	±5.0		V	1, 2, 3

(1) Parameter tested go-no-go, only.

LM160H/883 Electrical Characteristics AC Parameters

The following conditions apply, unless otherwise specified. V_{CC} = ±5V, f = 10MHz (sinusoidal)

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
t _{Resp}	Response Time	V _{IN} = 30mV _{P-P}	See ⁽¹⁾		25	nS	9
t _{Resp}	Response Time	V _{IN} = 2 V _{P-P}	See ⁽¹⁾		20	nS	9

(1) Bench test, use 70256644.

Typical Performance Characteristics

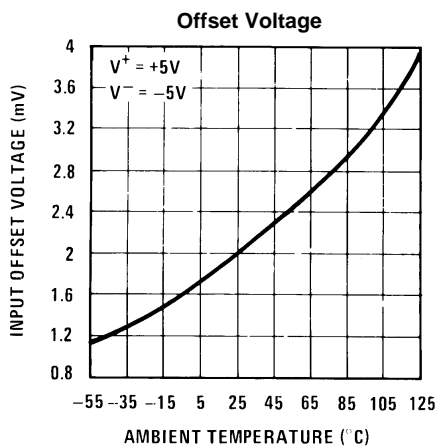


Figure 2.

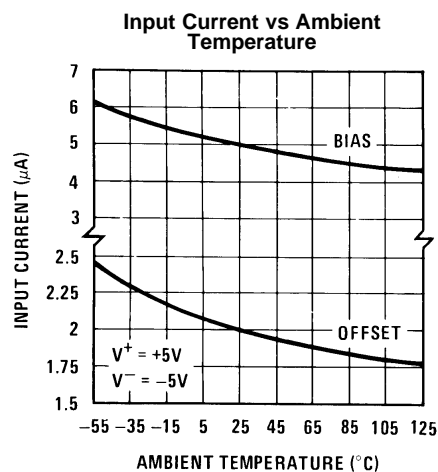


Figure 3.

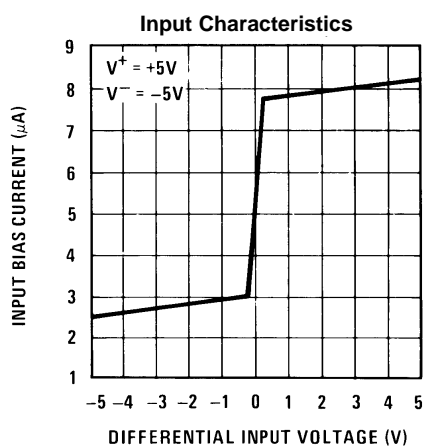


Figure 4.

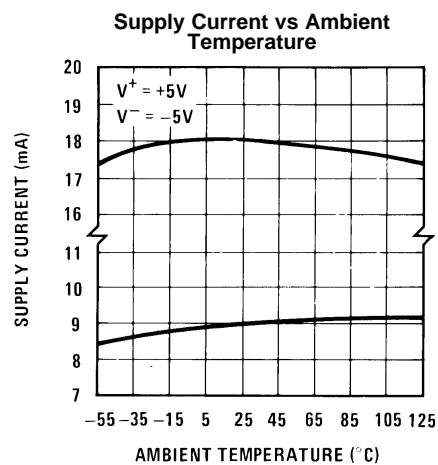


Figure 5.

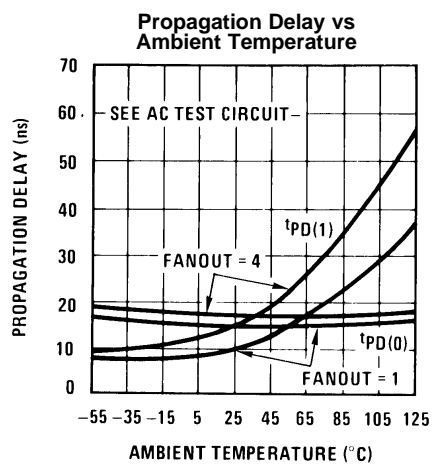


Figure 6.

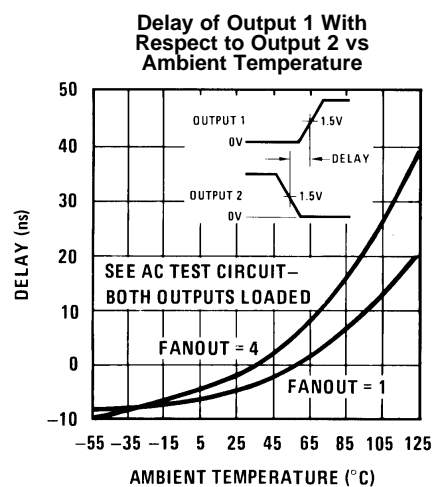


Figure 7.

Typical Performance Characteristics (continued)
Common-Mode Pulse Response

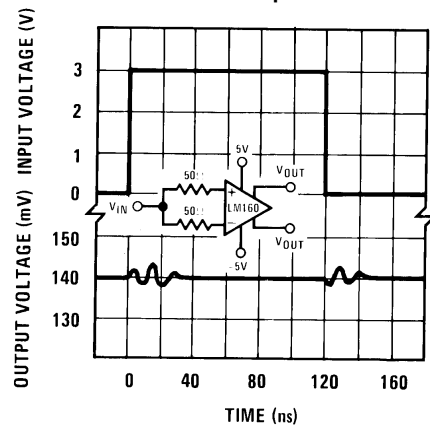
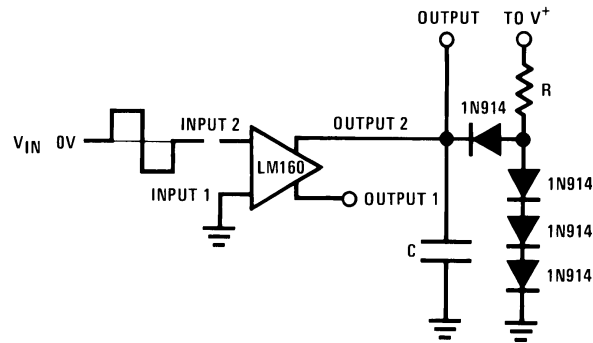


Figure 8.

AC Test Circuit



$V_I = \pm 50 \text{ mV}$

$V^+ = +5\text{V}$

$V^- = -5\text{V}$

FANOUT=1

$R = 2.4\text{k}\Omega$

$C = 15 \text{ pF}$

FANOUT=4



$R = 630\Omega$

$C = 30 \text{ pF}$

REVISION HISTORY

Released	Revision	Section	Changes
11/30/2010	A	New Release, Corporate format	1 MDS data sheets converted into one Corp. data sheet format. The drift table was eliminated since it did not apply MNL160-X Rev 0BL will be archived.
03/26/2013	A	All Sections	Changed layout of National Data Sheet to TI format

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-8767401GA	ACTIVE	TO-99	LMC	8	20	TBD	Call TI	Call TI	-55 to 125	LM160H/883 5962-8767401GA Q A CO 5962-8767401GA Q > T	
LM160H/883	ACTIVE	TO-99	LMC	8	20	TBD	Call TI	Call TI	-55 to 125	LM160H/883 5962-8767401GA Q A CO 5962-8767401GA Q > T	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

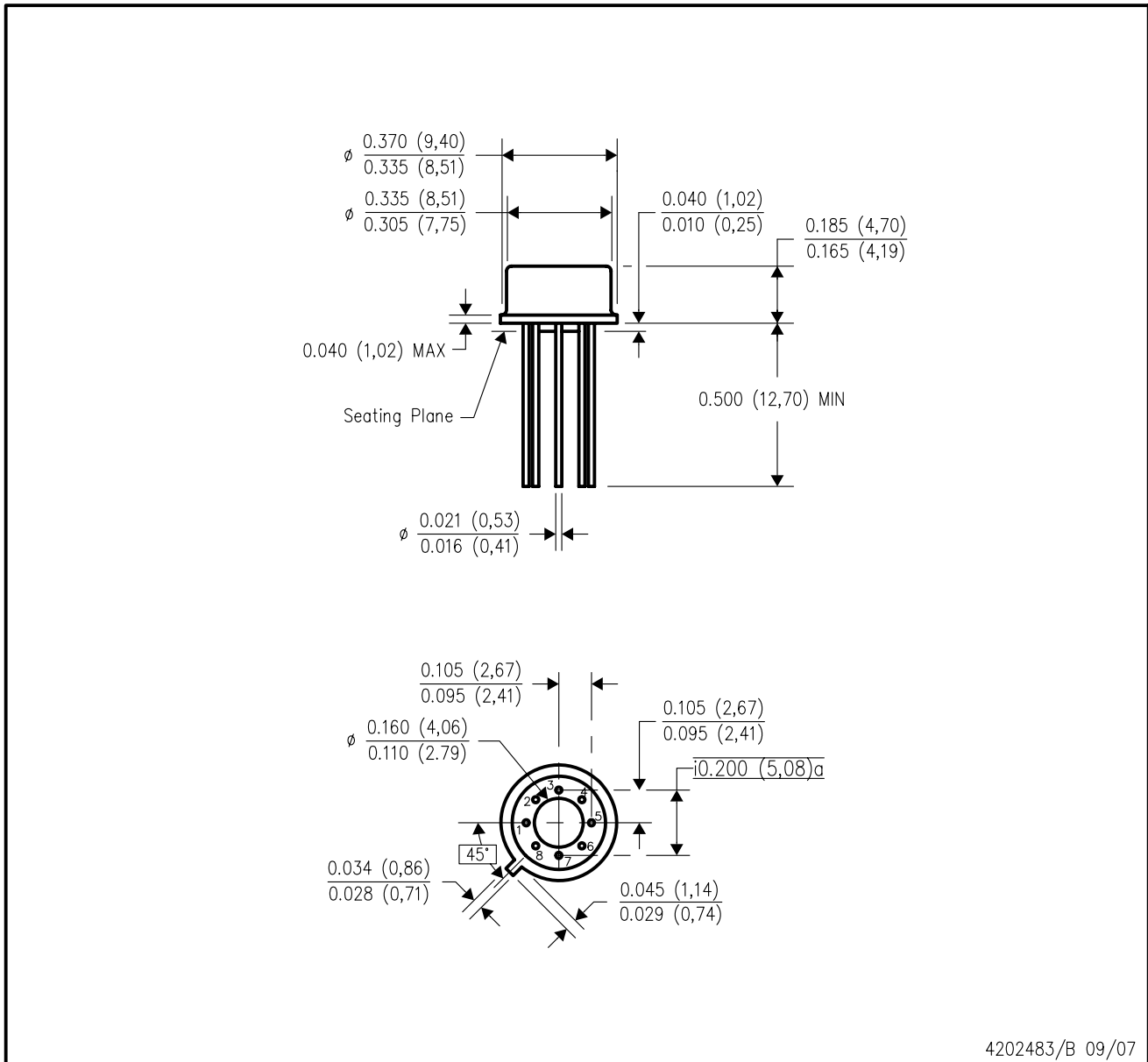
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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LMC (O-MBCY-W8)

METAL CYLINDRICAL PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Leads in true position within 0.010 (0,25) R @ MMC at seating plane.
 - D. Pin numbers shown for reference only. Numbers may not be marked on package.
 - E. Falls within JEDEC MO-002/TO-99.

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